

Intel[®] Server Board SE7320VP2 Memory Test List

Revision 54.0
September 2008

Revision History

Date	Rev	Modifications
Sept/04	1.0	Release revision.
Oct/04	2.0	Added Micron* 256MB part. Added Infineon* and Hynix* 1GB parts. (In shaded area)
Oct/04	3.0	Added Infineon 256MB parts. Added ATP*, Infineon and Hynix 512MB parts. (In shaded area)
Nov/04	4.0	Added TRS* 512MB, 1GB, and 2GB parts. Added ATP and Smart* 512MB and 1GB parts. Added Hynix 1GB part. (In shaded area)
Nov/04	5.0	Added Ventura*, TRS and Kingston* 1GB parts. Added Ventura and Smart 2GB parts. (In shaded area)
Dec/04	6.0	Added Apacer* 512MB and 1GB parts. Added TRS 1GB parts. (In shaded area)
Dec/04	7.0	Added Legacy* and Viking* 1GB parts. (In shaded area)
Dec/04	8.0	Added Micron 256MB part, Hynix 512MB part and Legacy 2GB parts. (In shaded area)
Dec/04	9.0	Added Viking and Apacer 2GB parts. (In shaded Area)
Jan/05	10.0	Added Legacy 512MB and Smart 1GB parts. (In shaded area)
Jan/05	11.0	Added Infineon 1GB and Smart 2GB parts. (In shaded area)
Feb/05	12.0	Added ATP 2GB parts. (In shaded area)
Feb/05	13.0	Added Samsung* 256MB part. Added Legacy 1GB and ATP 2GB parts. (In shaded area)
Mar/05	14.0	Added Ventura and Samsung 512MB parts. Added Samsung, Smart and ATP 1GB parts. Added Infineon 2GB part. (In shaded area)
Mar/05	15.0	Added note on Lead free modules (these modules are now in bold text). Added Legend 256MB, 512MB and 1GB parts. Added Ventura, Samsung and Dane-elec* 1GB parts. Added Dataram* and Infineon 2GB parts. (In shaded area)
Apr/05	16.0	Added Dataram, Ventura, Dane-Elec and Hynix 512MB parts. Added Dataram 1GB and 2GB parts. Added Micron 2GB part. (In shaded area)
Apr/05	17.0	Added Kingston 512MB and 2GB parts. Added Samsung 512MB parts. Added Ventura, Wintec*, and Dataram 1GB parts. (In shaded area)
May/05	18.0	Added Simple* 512MB and 1GB parts. Added Micron 512MB part. Added Samsung, Micron and Infineon 1GB parts. Added Netlist* 2GB parts. (In shaded area)
May/05	19.0	Added Avant* 512MB and 2GB parts. Added Dataram 1GB parts. (In shaded area)
June/05	20.0	Added support for DDR2-400 DDR II modules. Added Infineon, Micron and Samsung DDR2 256MB parts. Added Samsung and Infineon DDR2 512MB parts. Added Micron, Infineon and Samsung DDR2 1GB parts. Added Hynix, Samsung and Infineon DDR2 2GB parts. Replaced Low Profile column with Lead-Free. Added Dataram 1GB parts. Added Avant 2GB parts. (In shaded area)
Jun/05	21.0	Added Wintec, Samsung and Micron 512MB parts. Added Samsung and Micron 1GB parts. Added Dataram and Samsung 2GB parts. Added Samsung 4GB part (In shaded area)

Date	Rev	Modifications
Aug/05	22.0	Added Kingston 512MB parts. Added Hynix, Infineon, Samsung, Dataram and Kingston 1GB parts. Micron 512MB, 1GB, 2GB and 4GB parts. (In shaded area)
Aug/05	23.0	Added Kingston 1GB parts. Added Dataram 4GB parts. Added TRS 2GB parts. Added ATP, Kingston, Legacy, Smart, Viking and Wintec DDR2 1GB parts. Added Smart, Kingston and Dataram DDR2 2GB parts. Added Viking, Samsung and Infineon DDR2 512MB parts. (In shaded area)
Sept/05	24.0	Added Wintec and Samsung 2GB part. Added Kingston 512MB part. (In shaded area)
Oct/05	25.0	Added Ventura and Micron 512MB parts. Added Smart, Dataram and Samsung 1GB parts. (In shaded area)
Oct/05	26.0	Added Wintec, Dataram and Hynix DDR2 512MB parts. Added Legend and Legacy 1GB parts. Added Dataram, Kingston and Samsung DDR2 1GB parts. Added Kingston 2GB part. (In shaded area) Updated unleaded parts to correct shading.
Nov/05	27.0	Added Samsung 256MB parts. Added Apacer, Hynix and Samsung 512MB parts. Added Dataram, Hynix, Avant, Samsung and Legend 1GB parts. Added Smart, Samsung, Hynix and Micron 2GB parts. Added Infineon 4GB part. (In shaded area)
Nov/05	28.0	Updated two Micron 1GB parts with corrected DRAM part numbers. (in shaded area)
Dec/05	29.0	Added Legend 1GB part. Added Kingston DDR 1GB part. Added Legacy DDR2 2GB part. Added Smart DDR2 4GB part. (In shaded area)
Jan/06	30.0	Added Kingston DDR2 4GB, 2GB and 512MB parts. Added ATP DDR 4GB and DDR2 2GB parts. Added Samsung 1GB and 2GB parts. (In shaded area)
Jan/06	31.0	Added Legend 1GB part. Added Ventura DDR2 1GB part. Added Apacer DDR2 512MB part. Added Samsung DDR1 256MB, 512MB, 1G & 2G parts. Added Samsung DDR2 2G part. Added Hynix DDR2 512MB, 1G & 4G parts. (In shaded area)
Feb/06	32.0	Added Kingston, Wintec and Apacer DDR2 1GB parts. Added Infineon DDR1 512MB, 1G & 2G parts. Added Hynix DDR2 1G & 2G parts. (In shaded area)
Mar/06	33.0	Added Dataram 1GB part. Added TRS 2GB part. Added Smart and Legacy DDR2 1GB parts. Added Legacy and ATP DDR2 512MB parts. Added Legend DDR2 2GB parts. (In shaded area)
Mar/06	34.0	Added TRS 512MB, 1GB and 2GB parts. Added Dataram 2GB part. Added TRS DDR2 512MB and 2GB parts. Added Legend DDR2 512MB part. Added Smart DDR2 1GB part. (In shaded area)
May/06	35.0	Infineon name change to Qimonda effective May 1 st , 2006. Added TRS 512MB & 1G parts. Smart 512MB parts. Added Kingston and Dataram 1G, 2G & 4G parts. (In shaded area)
June/06	36.0	Added Buffalo 512MB DDR1 part. Added Dataram 512MB, 1G and 2G DDR2 parts. Added Kingston 1G and 2G DDR2 parts. Added Smart 1G DDR2 part. (In shaded area)
July/06	37.0	Added TRS 512MB part. Added TRS, Kingston, and Smart 1GB parts. Added Kingston 2GB part. (In shaded area)
July/06	38.0	Added TRS 512MB part. Added TRS, Kingston, and Smart 1GB parts. Added Kingston 2GB part. (In shaded area)
Aug/06	39.0	Added Kingston 512MB and 2GB parts. (In shaded area)

Date	Rev	Modifications
Aug/06	40.0	Added TRS 2GB part. (In shaded area)
Oct/06	41.0	Added TRS and Super Talent Electronics 512MB parts. Added TRS, Super Talent Electronics, Avant Technology, and Kingston 1GB parts. Added Super Talent Electronics 2GB part. (In shaded area)
Nov/06	42.0	Added Kingston 512MB, 1GB, and 2GB parts. (In shaded area)
Jan/07	43.0	Added Kingston 1GB part. Added Kingston, Smart, and ATP Electronics 2GB parts. (In shaded area)
Jan/07	44.0	Added Smart Modular Technologies 4GB part. (In shaded area)
Feb/07	45.0	Added All Components and TRS 1GB parts. Added Kingston 4GB part. Updated vendor contact information. (In shaded area)
Mar/07	46.0	Updated contact information. Added Kingston 512MB part. Added US Technology 1GB part. (In shaded area)
May/07	47.0	Added Dataram 512MB part. Added Dataram and Kingston 1GB parts. Added Kingston 2GB parts. (In shaded area)
May/07	48.0	Additional memory parts added. (In shaded area)
Jul/07	49.0	Additional memory parts added. (In shaded area)
Nov/07	50.0	Additional memory parts added. (In shaded area)
Jan/08	51.0	Additional memory parts added. (In shaded area)
Mar/08	52.0	Additional memory parts added. (In shaded area)
May/08	53.0	Additional memory parts added. (In shaded area)
Sept 08	54.0	Additional memory parts added. (In shaded area)

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The Intel® Server Board SE7320VP2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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Please Note: DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each Rank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each Rank on the memory module is NOT recommended.

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1. Overview of Memory Testing

The following test processes are used to qualify Dual In-Line Memory Modules (DIMMs) for use with the Intel® Server Board SE7320VP2. Memory is a vital subsystem in a server. Intel requires that strict guidelines be met before a DIMM vendor is added to the Tested memory List. To be included on the list as a fully supported DIMM, the memory must undergo rigorous tests to ensure that the product will perform the intended server product functions. Memory qualification for Intel® Server, Workstation, and RAID Controller products is performed both by Intel's Memory Validation Lab (MVL) and by an independent external test lab, Computer Memory Test Lab* (CMTL).

The Tested Memory Lists for Intel's server board, Workstation board, and RAID controller products categorize memory modules as Advanced Tested. The Advanced Testing process includes a standard paper qualification and then is followed by two levels of functional testing. DIMMs that have completed and passed Advanced Testing are considered to be compatible with the product on which they were tested, and with the test software and operating systems that was used during the test process.

1.1 Paper Qualification

A paper qualification is performed to verify that the specifications of a given DIMM meet Intel's memory specifications for a given product. Specification criteria reviewed include: critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements.

1.2 Functional Testing

After a given DIMM passes the standard paper qualification, functionality of the DIMM is then tested with the intended Intel product. Two levels of functional testing is performed; Standard and Advanced.

Standard functional testing requires that the given DIMM and Intel product combination operate with no failures for a period of no less than 24 hours for both minimum and maximum DIMM configurations. Testing is performed using a Microsoft Window* operating system and a custom test package. The test systems operate with standard voltage and at room temperature.

Advanced functional testing requires that the given DIMM and Intel product combination operate with no failures for a period of no less than 24 hours for both minimum and maximum DIMM configurations. Testing is performed with multiple operating systems and various custom test packages. Each test configuration is tested with various voltage and temperature margin conditions.

1.3 Computer Memory Test Lab*

Computer Memory Test Lab*, also known as CMTL, is a leading memory test organization responsible for testing a broad range of memory products. A memory product, which receives a "PASS" after being tested by CMTL, means it functions correctly and consumers can use the product to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with Intel supplied equipment and procedures defined by Intel's various functional testing levels.

CMTL* Contact Info:

Office: (949) 716-8690
Fax: (949) 716-8691

Computer Memory Test Lab (CMTL)
24 Hammond Suite F
Irvine, CA 92618
<http://www.cmtlabs.com/>

2. Intel® Server Board SE7320VP2 Memory Subsystem

The Intel® Server Board SE7320VP2 is capable of supporting either DDR266/333 or DDR2-400 memory technologies depending on which baseboard SKU is being used.

NOTE: Industry naming conventions for equivalent memory technologies include the following:

- DDR266 = PC2100
- DDR333 = PC2700
- DDR2-400 = PC23200

The following maximum memory capacities are supported based on the number of DIMM slots provided and maximum supported memory loads by the chipset:

- 24GB maximum capacity for DDR266
- 16GB maximum capacity for DDR333 and DDR2-400

The minimum memory supported with the system running in single channel memory mode is:

- 256MB for DDR256, DDR333 and DDR2-400.

Supported DIMM capacities are as follows:

- DDR266 Memory DIMM sizes include: 256MB, 512MB, 1GB, 2GB, and 4GB.
- DDR333 Memory DIMM sizes include: 256MB, 512MB, 1GB, 2GB, and 4GB.
- DDR2-400 Memory DIMM sizes include: 256MB, 512MB, 1GB, 2GB, and 4GB.

2.1 Memory Population

The Intel® Server Board SE7320VP2 has six DIMM slots, or three DIMM banks. Both DIMMs in a bank should be identical (same manufacturer, CAS latency, number of rows, columns and devices, timing parameters etc.). Although DIMMs within a bank must be identical, the BIOS supports various DIMM sizes and configurations allowing the banks of memory to be different. Memory sizing and configuration is guaranteed only for qualified DIMMs approved by Intel.

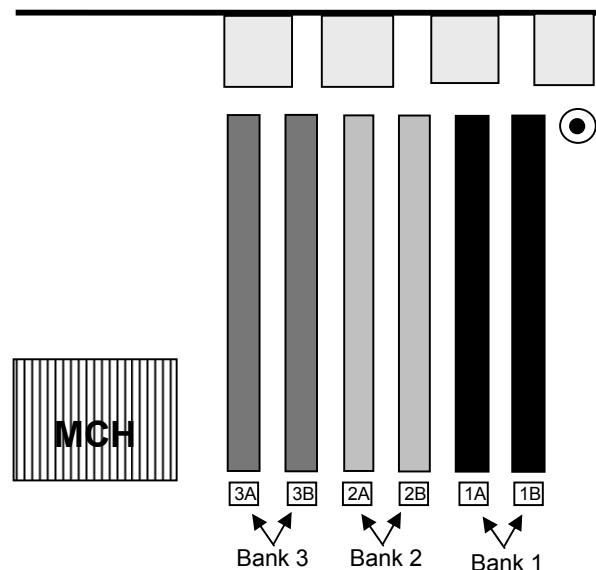


Figure 1. Identifying Banks of Memory

Mixing of DDR266, DDR333 and DDR2-400 DIMMs is supported between banks of memory. However, when mixing DIMM types, DDR333 will run at DDR266 speeds.

The memory controller is capable of supporting up to 4 loads per channel for DDR333. Memory technologies are classified as being either single rank or dual rank depending on the number of DRAM devices that are used on any one DIMM. A single rank DIMM is a single load device, i.e.) Single Rank = 1 Load. Dual rank DIMMs are dual load devices, i.e.) Dual Rank = 2 loads.

DDR266 and DDR333 DIMM population rules are as follows:

- (1) DIMM banks must be populated in order starting with the slots furthest from MCH
- (2) Single rank DIMMs must be populated before dual rank DIMMs
- (3) A maximum of four DIMMs can be populated when all four DIMMs are dual rank DDR333 DIMMs.

DDR2-400 DIMM population rules are as follows:

- (1) DIMMs banks must be populated in order starting with the slots furthest from MCH
- (2) Dual rank DIMMs are populated before single rank DIMMs
- (3) A maximum of four DIMMs can be populated when all four DIMMs are dual rank DDR2-400 DIMMs

The following tables show the supported memory configurations:

- s/r = single rank
- d/r = dual rank
- E = Empty

Table 1: Supported DDR266 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	D/R	D/R	D/R
	E	D/R	D/R
	E	E	D/R
	D/R	S/R	S/R
	D/R	D/R	S/R
	E	D/R	S/R

Table 2: Supported DDR333 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	E	D/R	D/R
	E	E	D/R
	D/R	S/R	S/R
	E	D/R	S/R

Table 3: Supported DDR2-400 DIMM Populations

MCH	Bank 3 – DIMMs 3A, 3B	Bank 2 – DIMMs 2A, 2B	Bank 1 – DIMMs 1A, 1B
	S/R	S/R	S/R
	E	S/R	S/R
	E	E	S/R
	E	D/R	D/R
	E	E	D/R
	E	S/R	D/R
	S/R	S/R	D/R

Note: On the Intel® Server Board SE7320VP2, when using all dual rank DDR333 or DDR2-400 DIMMs, a total of four DIMMs can be populated. Configuring more than four dual rank DDR333 or DDR2-400 DIMMs will result in the BIOS generating a memory configuration error.

2.2 Identifying “Single Rank” or “Double Ranked” DIMMs

- **x8SR** = x8 *Single-Ranked modules* - have 5 DRAMs on the front and 4 DRAMs on the back with empty spots in between the DRAMs.
- **x8DR** = x8 *Double-Ranked modules* - have 9 DRAMs on each side for a total of 18 (no empty slots)
- **x4SR** = x4 *Single-Ranked modules* - have 9 DRAMs on each side for a total of 18 – and look similar to x8 Double-Ranked
- **x4DR** = x4 *Double-Ranked modules* - have 18 (stacked) DRAMs on each side for a total of 36

The table below lists the current supported memory types:

DDR266 Registered SDRAM Module Matrix						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11	Single Ranked
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10	Double Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11	Single Ranked
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11	Double Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11	Double Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12	Single Ranked
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12	Double Ranked
4GB	512M x 72	1Gbit	512M x 72	36/2/4	14/2/12	Double Ranked

DDR333 Registered SDRAM Module Matrix						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11	Double Ranked
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10	Double Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11	Single Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12	Single Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11	Double Ranked
1GB	128M x 72	1Gbit	128M x 4	9/1/4	14/2/11	Single Ranked
2GB	256M x 72	1Gbit	128M x 4	18/1/4	14/2/12	Single Ranked
2GB	256M x 72	1Gbit	128M x 8	18/2/4	14/2/11	Double Ranked
4GB	TBD	TBD	TBD	TBD	TBD	TBD

DDR2-400 Registered SDRAM Module Matrix						
DIMM Capacity	DIMM Organization	SDRAM Density	SDRAM Organization	# SDRAM Devices/rows/Ranks	# Address bits rows/Ranks/column	Ranked
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10	Single Ranked
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11	Single Ranked
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10	Double Ranked
512MB	64M x 72	512Mbit	64M x 8	9/1/4	14/2/10	Single Ranked
1GB	128M x 72	512Mbit	128M x 4	18/1/4	14/2/11	Single Ranked
1GB	128M x 72	512Mbit	64M x 8	18/2/4	14/2/10	Double Ranked
1GB	128M x 72	1Gbit	128M x 8	9/1/8	14/3/10	Single Ranked
2GB	256M x 72	1Gbit	256M x 4	18/1/8	14/3/11	Single Ranked
2GB	256M x 72	1Gbit	128M x 8	18/2/8	14/3/10	Double Ranked
2GB	256M x 72	2Gbit	256M x 8	9/1/8	15/3/10	Single Ranked
4GB	512M x 72	2Gbit	256M x 8	18/2/8	15/3/10	Double Ranked
4GB	512M x 72	2Gbit	512M x 4	18/1/8	15/3/11	Single Ranked
4GB	512M x 72	4Gbit	512M x 8	9/1/8	TBD	Single Ranked

3. Tested Memory

The following tables list DIMM devices tested to be compatible with the Intel® Server Board SE7320VP2. The list of tested memory is periodically updated as qualified memory is added during the production life of the Intel product.

Intel strongly recommends the use of ECC memory in all server products.

Memory modules not listed in the following tables have not been tested for compatibility and their use with the Intel® Server Board SE7320VP2 may result in unpredictable operation and data loss.

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy. This list is subject to change without notice.

Note: This list is not intended to be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

Intel® Server Board SE7320VP2
Registered ECC, DDR266 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Micron*	MT9VDDT3272G-265G3	MT46V32M8-6T G	Micron		10/1/04		(32Mx8)*9	SR	
+Legend*	L3272YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1	3/9/05		(32Mx8)*9	SR	

Registered ECC, DDR333 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Samsung*	M312L3223EG0-CB3	K4H560838E-GCB3	Samsung		9/12/04		(32Mx8)*9	SR	
Qimonda*	HYS72D32300GB R-6-C	HYB25D256800CC-6	Qimonda		10/25/04		(32Mx8)*9	SR	
Qimonda	HYS72D32300GB R-6-B	HYB25D256800BC-6	Qimonda		10/25/04		(32Mx8)*9	SR	
Micron	MT9VDDF3272G-335G3	MT46V32M8FG-6	Micron		12/17/04		(32Mx8)*9	SR	
Samsung	M312L3223EZ0-CB3	K4H560838E-ZCB3	Samsung		2/24/05	Yes	(32Mx8)*9	SR	
Samsung	M312L3223EG3-CB3	K4H560838E-GCB3	Samsung		11/15/05		(32Mx8)*9	SR	
Samsung	M312L3223EZ3-CB3	K4H560838E-ZCB3	Samsung		11/15/05	Yes	(32Mx8)*9	SR	

Registered ECC, DDR2-400 DIMM Modules
256MB Size (32M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Qimonda	HYS72T32000HR-5-A	HYB18T256800AF5-A	Qimonda		5/23/05	Yes	(32Mx8)*9	SR	
Micron	MT9HTF3272Y-40EB2	MT47H32M8BP-37E	Micron		5/23/05	Yes	(32Mx8)*9	SR	
Samsung	M393T3253FG0-CCC	K4T56083QF-GCCC	Samsung		5/23/05		(32Mx8)*9	SR	
Samsung	M393T3253FZ0-CCC	K4T56083QF-ZCCC	Samsung		5/23/05	Yes	(32Mx8)*9	SR	
Samsung	M393T3253FG3-CCC	K4T56083QF-GCCC	Samsung		11/4/05		(32Mx8)*9	SR	
Samsung	M393T3253FZ3-CCC	K4T56083QF-ZCCC	Samsung		11/4/05	Yes	(32Mx8)*9	SR	

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Intel® Server Board SE7320VP2
Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Micron	MT18VDDT6472G-265G3	MT46V64M4-75 G	Micron		9/13/04		(32Mx8)* 18	DR	
+TRS*	TRS21202	HYB25D256400CE-7 rev C	Qimonda	M0530LA1 rev 1	11/4/04		(64Mx4)* 18	SR	
+TRS	TRS21151	HYB25D256400BT-7 rev B	Qimonda	M0530LA1 rev 1	11/10/04		(64Mx4)* 18	SR	
+TRS	TRS21152	HYB25D256800BT-7 rev B	Qimonda	M0529LA1 rev 1	11/9/04		(32Mx8)* 18	DR	
+Legend	L6472YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1	3/9/05		(32Mx8)* 18	DR	
Hynix	HYMD264G726D4 M-H	HY5DU56422DT-H	Hynix		4/6/05		(64Mx4)* 18	SR	
Samsung	M312L6420ETS-CB0	K4H560438E-TCB0	Samsung		4/13/05		(64Mx4)* 18	SR	
Samsung	M312L6420EUS-CB0	K4H560438E-UCB0	Samsung		4/13/05	Yes	(64Mx4)* 18	SR	

Registered, ECC, DDR333 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Qimonda	HYS72D64300GB R-6-B	HYB25D256400BC-6	Qimonda		9/4/04		(64Mx4)* 18	SR	
+ATP Electronics*	AB64L72L4BFB3C	HYB25D256400BC-5 rev B	Qimonda	SB184L04L1	10/25/04		(64Mx4)* 18	SR	
Qimonda	HYS72D64300GB R-6-C	HYB25D256400CC-6	Qimonda		10/25/04		(64Mx4)* 18	SR	
Qimonda	HYS72D64320GB R-6-C	HYB25D256800CC-6	Qimonda		10/25/04		(32Mx8)* 18	DR	
Hynix*	HYMD564G72BF8 N-J AA	HY5DU12822BF-J	Hynix		10/27/04		(64Mx8)* 9	SR	
+ATP Electronics	AB64L72L4BFB3C	HYB25D256400BC-5 rev B	Qimonda	SB184L04L1	10/25/04		(64Mx4)* 18	SR	
+ATP Electronics	AB64L72L4BFB3S	K4H560438E-GCB3 rev E	Samsung	SB184L04L1	11/8/04		(64Mx4)* 18	SR	
+Smart Modular Technologies*	SM6472RDDR6H1 BGBC	HYB25D256400CC-6 rev C	Qimonda	184-22-2	11/1/04		(64Mx4)* 18	SR	
+Apacer*	75.96299.555	HYB25D256400CC-6 rev C	Qimonda	48.16164.013 rev C	11/24/04		(64Mx4)* 18	SR	
Hynix	HYMD264G726DF 4N-J AA	HY5DU564220-F-J	Hynix		12/17/04				
+Legacy Electronics Inc.*	88S6JDGR-1NDG	HYB25D256400BC6 rev B	Qimonda	LE36DDF1844RC rev B	1/6/05		(64Mx4)* 18	SR	
+Ventura Technology Group*	D52YCK44SV	K4H560438E-GCB3 rev E	Samsung	DR1G472B	2/22/05		(64Mx4)* 18	SR	
Samsung	M312L6420EG0-CB3	K4H560438E-GCB3	Samsung		2/25/05		(64Mx4)* 18	SR	

Registered, ECC, DDR333 DIMM Modules 512 MB Sizes (64Mx72)									
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Samsung	M312L6420EZ0-CB3	K4H560438E-ZCB3	Samsung		2/25/05	Yes	(64Mx4)* 18	SR	
+Dataram	DTM63676D	HYB25D256400CC-6 rev C	Qimonda	40018A rev A	3/16/05		(64Mx4)* 18	SR	
+Ventura Technology Group	D52YCK44MV	MT46V64M4FG-6 rev G	Micron	DR1G472B	3/25/05		(64Mx4)* 18	SR	
+Dane-Elec*	DLD333R072645H	MT46V64M4FG-5B rev G	Micron	DR1G472B	3/18/05		(64Mx4)* 18	SR	
+Kingston*	KVR333S4R25/51 2I	HYB25D256400CC-6 rev C	Qimonda	2025161-001.B00	4/7/05		(64Mx4)* 18	SR	
SimpleTech*	ST72E4K64ML-B06E	HYB25D256400CC-6 rev C	Qimonda	01269 rev A	4/18/05		(64Mx4)* 18	SR	
Micron	MT18VDDF6472G-335G3	4AGII D9BJR	Micron		5/3/05		(64Mx8)* 9	SR	
+Avant Technology	AVM7264R38C533 3K6-MTG	MT46V64M4FG-5B rev G	Micron	RCE0020-01 rev 1	5/5/05		(64Mx4)* 18	SR	
+Wintec Industries*	3C944646-L	HYB25D256400CC-5 rev C	Qimonda	DR1G472B	6/8/05		(64Mx4)* 18	SR	
+Kingston	KVR333S4R25/51 2I	K4H560438E-GCB3 rev E	Samsung	2025161-001.B00 na	7/15/05		(64Mx4)* 18	SR	
Micron	MT9VDDF6472G-335D3	MT46V64M8FG	Micron		9/26/05		(64Mx8)* 9	SR	
Samsung	M312L6523CZ0-CB3	K4H510838C-ZCB3	Samsung		10/24/05	Yes	(64Mx8)* 9	SR	
Hynix	HYMD564G726CF P8N-J	HY5DU12822CFP-J	Hynix		10/25/05		(64Mx8)* 9	SR	
Samsung	M312L6420EG3-CB3	K4H560438E-GCB3	Samsung		11/15/05		(64Mx4)* 18	SR	
Samsung	M312L6420EZ3-CB3	K4H560438E-ZCB3	Samsung		11/15/05	Yes	(64Mx4)* 18	SR	
Samsung	M312L6523CZ3-CB3	K4H510838C-ZCB3	Samsung		11/15/05	Yes	(64Mx8)* 9	SR	
Qimonda	HYS72D256320HB R-6-C	HYB25D512400CF-6	Qimonda		1/31/06	Yes	(64Mx8)* 9	SR	
+TRS	TRS21220	HYB25D256400BC-6 rev B	Qimonda	M0545LA1 rev 1	3/9/06		(64Mx4)* 18	SR	
+TRS	TRS21180	HYB25D256400CC-6 rev C	Qimonda	M0545LA1 rev 1	3/15/06		(64Mx4)* 18	SR	
Kingston	KVR333S4R25/51 2I	HYB25D256400CF-5 rev C	Qimonda	2025161-001.B00 na	3/20/07	Yes	(64Mx4)* 18	SR	
Kingston	KVR333S4R25/51 2I	HYB25D256400CF-5 rev C	Qimonda	2025318-001.A00	09/23/08	Yes	64M x 4	SR	

**Registered, ECC, DDR2-400 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Samsung	M393T6453FG0-CCC	K4T56083QF-GCCC	Samsung		5/23/05		(32Mx8)* 18	DR	
Samsung	M393T6453FZ0-CCC	K4T56083QF-ZCCC	Samsung		5/23/05	Yes	(32Mx8)* 18	DR	
Samsung	M393T6450FG0-CCC	K4T56043QF-GCCC	Samsung		5/23/05		(64Mx4)* 18	SR	
Samsung	M393T6450FZ0-CCC	K4T56043QF-ZCCC	Samsung		5/23/05	Yes	(64Mx4)* 18	SR	
Qimonda	HYS72T64020HR-5-A	HYB18T256800AF5-A	Qimonda		6/6/05	Yes	(32Mx8)* 18	DR	
Qimonda	HYS72T64001HR-5-A	HYB18T256400AF5-A	Qimonda		6/6/05	Yes	(64Mx4)* 18	SR	
Samsung	M393T6553BG0-CCC	K4T51083QB-GCCC	Samsung		6/6/05		(64Mx8)* 9	SR	
Samsung	M393T6553CZ0-CCC	K4T51083QC-ZCCC	Samsung		6/20/05	Yes	(64Mx8)* 9	SR	
Micron	MT18HTF6472Y-40EB2	MT47H64M4BP-37E	Micron		6/20/05	Yes	(64Mx4)* 18	SR	
Micron	MT9HTF6472Y-40EB2	MT47H64M8CB-5E	Micron		7/18/05	Yes	(64Mx8)* 9	SR	
+Viking*	VR5ER647218EB PL1	MT47H64M8CB-37E rev B	Micron	0000992A rev A	07/26/05		(64Mx8)* 9	SR	
Samsung	M393T6553BZ0-CCC	K4T51083QB-ZCCC	Samsung		8/3/05	Yes	(64Mx8)* 9	SR	
Qimonda	HYS72T64000GR-5-A	HYB18T512800AC5	Qimonda		8/15/05		(64Mx8)* 9	SR	
Qimonda	HYS72T64000HR-5-A	HYB18T512800AC5	Qimonda		8/15/05	Yes	(64Mx8)* 9	SR	
+Kingston	KVR400D2S8R3/5 12I	HYB18T512800AF37 rev A	Qimonda	2025263-001.C00 na	9/13/05		(64Mx8)* 9	SR	
+Ventura Technology Group	D2-52KC53SV-333	K4T56043QF-ZCD5 rev F	Samsung	D2R472 na	9/26/05		(64Mx8)* 9	SR	
+Dataram	DTM63312A	HYB18T512800AF5 rev A	Qimonda	40042A rev A	10/11/05		(64Mx8)* 9	SR	
+Wintec Industries	39C921284B-GL	K4T51083QB-ZCD5 rev B	Samsung	D2R872 na	10/4/05		(64Mx8)* 9	SR	
Hynix	HYMP564R728-E3	HY5PS12821-F-E3	Hynix		10/12/05		(64Mx8)* 9	SR	
+Apacer	75.963A1.G01	EDE5108AGSE-5C-E rev G	Elpida	48.16188.01 1 rev 1	10/19/05	Yes	(64Mx8)* 9	SR	
Samsung	M393T6450FZ3-CCC	K4T56043QF-ZCCC	Samsung		10/24/05	Yes	(64Mx4)* 18	SR	
Samsung	M393T6450FG3-CCC	K4T56043QF-GCCC	Samsung		11/4/05		(64Mx4)* 18	SR	
Samsung	M393T6453FZ3-CCC	K4T56083QF-ZCCC	Samsung		11/4/05	Yes	(32Mx8)* 18	DR	
Samsung	M393T6453FG3-CCC	K4T56083QF-GCCC	Samsung		11/4/05		(32Mx8)* 18	DR	
Samsung	M393T6553CZ3-CCC	K4T51083QC-ZCCC	Samsung		11/4/05	Yes	(64Mx8)* 9	SR	
+Kingston	KVR400D2S8R3/5 12I	NT5TU64M8AE-37B rev A	Nanya	2025263-001.C00 na	12/14/05		(64Mx4)* 18	SR	

**Registered, ECC, DDR2-400 DIMM Modules
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
+Apacer	75.963A1.G02	K4T51083QC-ZCD5 rev C	Samsung	48.16188.011 rev 1	12/21/05	Yes	(64Mx8)* 9	SR	
Hynix	HYMP564R72P8-E3	HY5PS12821FP-E3	Hynix		1/10/06	Yes	(64Mx8)* 9	SR	
Hynix	HYMP564R72BP8-E3	HY5PS12821BFP-E3	Hynix		1/10/06	Yes	(64Mx8)* 9	SR	
+Legacy Electronics Inc.	B557K4C2AAA-50	K4T51083QC-ZCCC rev C	Samsung	LE9DD2F2408RRA rev A	2/10/06		(64Mx8)* 9	SR	
+ATP Electronics	AH64K72F8BHC4S	K4T51083QC-ZCD5 rev C	Samsung	SH240F08K1 na	2/28/06	Yes	(64Mx8)* 9	SR	
+Legend	L64723C7-R41H2H1F	HY5PS12821FP-E3 rev 1st Gen.	Hynix	104 (0530,0534)	3/10/06	Yes	(64Mx8)* 9	SR	
+TRS	TRS31260	HYB18T512800AF5 rev A	Qimonda	M0551LA1 rev 1	3/24/06	Yes	(64Mx8)* 9	SR	
Smart Modular Technologies	SG647RDR264835-SC	K4T51083QC-ZCCC rev C	Samsung	M393T6553BG1 (KS-11A)	04/05/06	Yes			
TRS	TRS31261	HYB18T256400AF5 rev A	Qimonda (Infineon)	M0549LA1 rev 1	04/10/06	Yes			
Buffalo	D2R400A-ES512MBJ	MT47H64M8CB-5E rev B	Micron	2DRA18F-BA na	04/27/06	Yes	(64Mx8)* 9	SR	
Dataram	DTM63312B	NT5TU64M8AE-37B rev A	Nanya	40042A rev A	05/02/06	Yes	(64Mx8)* 9	SR	
Dataram	DTM63311D	HYB18T256400AF5 rev A	Qimonda	40011A rev A	05/23/06	Yes			
TRS	TRS31260X	HYB18T512800AF5 rev A	Qimonda (Infineon)	M0551LA1 rev 1	7/3/06	Yes	(64Mx8)* 9		
Kingston	KVR400D2S8R3/512I	E5108AG-5C-E rev G	Elpida	2025263-001.C00 na	7/12/06	Yes	(64Mx8)* 9		
Super Talent Electronics	T400RA512/S12T R8BHS	K4T51083QC-ZCD5 rev C	Samsung	DR20809 rev F1.01	8/15/06	Yes	(64Mx8)* 9	SR	
TRS	TRS31261X	HYB18T256400AF5 rev A	Qimonda (Infineon)	M0549LA1 rev 1	8/29/06	Yes	(64Mx4)* 18	SR	
TRS	TRS31275	E5108AG-5C-E rev G	Elpida	M0551LA1 rev 1	9/15/06	Yes	(64Mx8)* 9	SR	
Kingston	KVR400D2S8R3/512I	E5108AGBG-6E-E rev G	Elpida	2025263-001.C00 na	11/2/06	Yes	(64Mx8)* 9	SR	
Dataram	DTM63312E	HY5PS12821CFP-Y5 rev C	Hynix	40042A rev A	4/19/07	Yes	(64Mx8)* 9	SR	

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Intel® Server Board SE7320VP2
Registered, ECC, DDR266 DIMM Modules
1GB Size (128M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Hynix	HYMD512G726B 4M-HAA	HY5DU12422BT-H	Hynix		10/1/04		(128Mx4)* *18	SR	
Hynix	HYMD512G726B 4M-HAA	HY5DU12422BT-H	Hynix		11/15/04		(128Mx4)* 18	SR	
+Ventura Technology Group	D54WYK42SV	K4H510838B-TCB3 rev B	Samsung	DR1G872-A	11/19/04		(64Mx8)* 18	DR	
+TRS	TRS21174	HYB25D512800AT- 7 rev A	Qimonda	M0529LA1 rev 1	11/17/04		(64Mx8)* 18	DR	
+TRS	TRS21171	HYB25D256400BC- 7 rev B	Qimonda	M0533LA1 rev 1	11/18/04		(64Mx4)* 36	DR	
+TRS	TRS21203	HYB25D512400BE- 7 rev B	Qimonda	M0530LA1 rev 1	11/22/04		(128Mx4)* 18	SR	
+Legend	L1272YC5- RU1HDH5A	HY5DU12822AT-H rev A	Hyundai	DRR1U0818 -A rev 1	3/11/05		(64Mx8)* 18	DR	
Samsung	M312L2828ET0- CB0	K4H510638E-TCB0	Samsung		6/20/05		(64Mx4)* 36	DR	
Micron	MT18VDDT12872 G-265D2	MT46V128M4TG-6T	Micron		6/20/05		(128Mx4)* 18	SR	
+Dataram	DTM63698C	HYB25D512400BT(BE)-6 rev B	Qimonda	40581A rev A	6/30/05	Yes	(128Mx4)* 18	SR	
Samsung	M312L2828EU0- CB0	K4H510638E-UCB0	Samsung		9/26/05	Yes	(64Mx4)* 36	DR	
+Legend	L1272YC5- 183HDD5A	HY5DU56422AS-H rev A	Hyundai	184RL rev 3	10/7/05		(64Mx4)* 36	DR	
Samsung	M312L2920CUS- CB0	K4H510438C-UCB0	Samsung		9/21/05	Yes	(128Mx4)* 18		
+Dataram	DTM63653R	HYB25D256400CF- 6 rev C	Qimonda	40599A rev A	2/7/06	Yes	(64Mx4)* 36	DR	
Smart Modular Technologies	SG12872RDDR3 08BTSC	K4H510838C-UCCC rev C	Samsung	PG52G184N EBZ6RCL rev A	05/18/06	Yes	(64Mx8)* 18	DR	

**Registered, ECC, DDR333 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Qimonda	HYS72D128320G-BR-6-C	HYB25D256400CC-6	Qimonda		9/1/04		(64Mx4)* 36	DR	
Qimonda	HYS72D128300G-BR-6-B	HYB25D512400BC-6 B	Qimonda		10/1/04		(128Mx4)* *18	SR	
+ATP Electronics	AB28L72Y4BFB3 C	HYB25D256400BC-5 rev B	Qimonda	SB184Y04L1	11/3/04		(64Mx4)* 36	DR	
+ATP Electronics	AB28L72L4BFB3 C	HYB25D512400BC-6 rev B	Qimonda	SB184L04L1	11/10/04		(128Mx4)* 18	SR	
+Smart Modular Technologies	SM12872RDDR6 H2BGIC	HYB25D256400CC-6 rev C	Qimonda	P54G184NE SZBRCD rev B	11/5/04		(64Mx4)* 36	DR	
+Smart Modular Technologies	SM12872RDDR6 H2BGAS	K4H560438E-GCB3 rev E	Samsung	P54G184NE SZBRCD rev B	11/11/04		(64Mx4)* 36	DR	
+TRS	TRS21197	HYB25D256400CC-6 rev C	Qimonda	M0533LA1 rev 1	11/12/04		(64Mx4)* 36	DR	
Kingston	KVR333X72RC25 /1G	HYB25D256400CC-6 rev C	Qimonda	2025247-001.A00	11/16/04		(64Mx4)* 36	DR	
+Apacer	75.07299.561	HYB25D512400BC-6 rev B	Qimonda	48.16164.01 3 rev C	11/24/04		(128Mx4)* 18	SR	
+Legacy Electronics Inc.	89S6MDZR-1NDG	HYB25D512400BC-6 rev B	Qimonda	LE18DDDF18 44R rev A	11/30/04		(128Mx4)* 18	SR	
+Viking	VI4CR287224DB KL2	K4H560438E-GCB3 rev E	Samsung	0000972B	12/2/04		(64Mx4)* 36	DR	
+Smart Modular Technologies	SM12872RDDR6 H1BGAI	HYB25D512400BC-6 rev B	Qimonda	P52G184NE SZBGAX rev A	12/21/04		(128Mx4)* 18	SR	
Qimonda	HYS72D128321G-BR-6-B	HYB25D512800BC-6 B	Qimonda		1/10/05		(64Mx8)* 18	DR	
+Legacy Electronics Inc.	89S6JDGM-1NDG	HYB25D256400BC6 rev B	Qimonda	LE36DDDF18 44RRF rev A	2/2/05		(64Mx4)* 36	DR	
+Smart Modular Technologies	SM12872RDDR6 H1BGBI	HYB25D512400BC-6 rev B	Qimonda	184-22-2	2/23/05		(128Mx4)* 18	SR	
+ATP Electronics	AB28L72L4BFB3 M	MT46V128M4FN-5B rev D	Micron	SB184L04L1	2/18/05		(128Mx4)* 18	SR	
+ATP Electronics	AB28L72L4BFB3 S	K4H510438C-ZCB3 rev C	Samsung	SB184L04L1	2/22/05		(128Mx4)* 18	SR	
Samsung	M312L2820EG0-CB3	K4H510438B-GCB3	Samsung		3/2/05		(64Mx4)* 36	DR	
+Ventura Technology Group	D54YFK44MV	MT46V128M4FN-6 rev D	Micron	DR1G472B	3/2/05		(128Mx4)* 18	SR	
+Dane-Elec	DLD333R072285 M	MT46V128M4FN-5B rev D	Micron	DR1G472B	3/4/05		(128Mx4)* 18	SR	

**Registered, ECC, DDR333 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Samsung	M312L2820EG0-CB3	K4H510438B-GCB3	Samsung		3/2/05		(64Mx4)* 36	DR	
+Dataram	DTM63677F	HYB25D256400CC-6 rev C	Qimonda	40599A rev A	3/22/05		(64Mx4)* 36	DR	
+Ventura Technology Group	D54YFK44SV	K4H510438C-ZCB3 rev C	Samsung	DR1G472B	3/30/05		(128Mx4)* 18	SR	
Wintec Industries	3C954641D-L	HYB25D256400CC-5 rev C	Qimonda	ZK4096M84 RCJB	4/5/05		(64Mx4)* 36	DR	
+Dataram	DTM63677F	HYB25D256400CC-6 rev C	Qimonda	40599A rev A	3/22/05		(64Mx4)* 36	DR	
SimpleTech	ST72E4L128ML-B06E	HYB25D512400BC-6 rev B	Qimonda	01269 rev A	4/20/05		(128Mx4)* 18	SR	
Samsung	M312L2920CZ0-CB3	K4H510438C-ZCB3	Samsung		5/3/05	Yes	(128Mx4)* 18	SR	
Micron	MT36VDDF12872 G-335G3	MT46V64M4FG-6	Micron		5/3/05		(64Mx4)* 36	DR	
Qimonda	HYS72D128300G BR-6-B	HYB25D512400BC-6 B	Qimonda		5/3/05		(128Mx4)* 18	SR	
+Dataram	DTM63694B	K4H510438C-ZCB3 rev C	Samsung	40018A rev A	5/16/05		(128Mx4)* 18	SR	
Samsung	M312L2820EZ0-CB3	K4H510438B-GCB3	Samsung		6/22/05	Yes	(64Mx4)* 36	DR	
+Kingston	KVR333S4R25/1 GI	HYB25D512400BC-6 rev B	Qimonda	2025318-001.A00 na	7/5/05		(128Mx4)* 18	SR	
Micron	MT18VDDF12872 G-335D3	MT46V128M4FN-6	Micron		7/8/05		(128Mx4)* 18	SR	
Hynix	HYMD512G726B F4N-J	HY5DU12422B-F-J	Hynix		7/25/05		(64Mx4)*1 8		
Samsung	M312L2923CZ0-CB3	K4H510838C-ZCB3	Samsung		7/25/05	Yes	(64Mx8)*1 8	DR	
+Kingston	KVR333D4R25/1 GI	K4H560438E-GCB3 rev E	Samsung	2025247-001.A00 na	08/09/05		(64Mx4)* 36	DR	
+Dataram	DTM63677F	HYB25D256400CC-6 rev C	Qimonda	40599A rev A	3/22/25		(64Mx4)* 36	DR	
+Legacy Electronics Inc.	89B6MDZR-1NDG	K4H510438C-ZCB3 rev C	Samsung	LE18DDF1844R rev A	10/14/05		(128Mx4)* 18	SR	
+Avant Technology	AVM7228R53C5333K6-NYBP	NT5DS128M4BG-6K rev B	Nanya	RCE0020-01 rev 1	10/28/05		(128Mx4)* 18	SR	
Hynix	HYMD512G726C FP4N-J	HY5DU12422CFP-J	Hynix		10/24/05		(128Mx4)* 18	SR	
+Legend	L1272YC6-PPXSMD1B	K4H510438B-GCB3 rev B	Samsung	M312L6420 G0 na	12/1/05		(128Mx4)* 18	SR	
+Legend	L1272YC6-PPXSDD2E	K4H560438E-GCB3 rev E	Samsung	DR2G472B na	1/11/06		(64Mx4)* 36	DR	
Samsung	M312L2920CZ3-CB3		Samsung		11/15/05	Yes	(128Mx4)* 18	SR	

Registered, ECC, DDR333 DIMM Modules 1GB Size (128M x 72)									
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Samsung	M312L2923CZ3-CB3		Samsung		11/15/05	Yes	(64Mx8)*18	DR	
Samsung	M312L2820EG3-CB3		Samsung		11/15/05		(64Mx4)*36	DR	
Samsung	M312L2820EZ3-CB3		Samsung		11/15/05	Yes	(64Mx4)*36	DR	
Qimonda	HYS72D128321HBR-6-C	HYB25D512800CF-6	Qimonda		1/31/06	Yes	(64Mx8)*18	DR	
Qimonda	HYS72D128300HBR-6-C	HYB25D512400CF-6	Qimonda		1/31/06	Yes	(128Mx4)*18	SR	
+TRS	TRS21196	HYB25D256400BC-6 rev B	Qimonda	M0533LA1 rev 1	3/13/06		(64Mx4)*36	DR	
+TRS	TRS21229	HYB25D512400BC-6 rev B	Qimonda	M0545LA1 rev 1	3/20/06		(128Mx4)*18	SR	
Kingston	KVR333D4R25/1GI	HYB25D256400CF-5 rev C	Qimonda (Infineon)	2025247-001.A00 na	3/30/06	Yes			
Kingston	KVR333S4R25/1GI	K4H510438C-ZCB3 rev C	Samsung	2025324-001.A00 na	8/22/06	Yes	(128Mx4)*18	SR	
Kingston	KVR333S4R25/1GI	K4H510438C-ZCCC rev C	Samsung	2025324-001.A00 na	10/5/06	Yes	(128Mx4)*18	SR	
Kingston	KVR333S4R25/1GI	HYB25D512400CF-5 rev C	Qimonda	2025324-001.A00 na	4/30/07	Yes	(128Mx4)*18	SR	
Kingston	KVR333S4R25/1GI	HYB25D512400BF-5 rev B	Qimonda	2025324-001.A00 na	9/26/07	Yes	(128Mx4)*18	SR	

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Micron	MT18HTF12872Y-40EA2	MT47H64M8BT-5E	Micron		5/23/05	Yes	(128Mx4)* 18	SR	
Samsung	M393T2950BG0-CCC	K4T51043QB-GCCC	Samsung		5/23/05		(128Mx4)* 18	SR	
Samsung	M393T2950BZ0-CCC	K4T51043QB-ZCCC	Samsung		5/23/05	Yes	(128Mx4)* 18	SR	
Samsung	M393T2953BG0-CCC	K4T510830B-GCCC	Samsung		5/23/05		(64Mx8)* 18	DR	
Samsung	M393T2953BZ0-CCC	K4T51083QB-ZCCC	Samsung		5/23/05	Yes	(64Mx8)* 18	DR	
Samsung	M393T2953CZ0-CCC	K4T510830C-ZCCC	Samsung		5/23/05	Yes	(64Mx8)* 18	DR	
Qimonda	HYS72T128000HR-5-A	HYB18T512400AF5	Qimonda		6/6/05	Yes	(128Mx4)* 18	SR	
Qimonda	HYS72T128020HR-5-A	HYB18T512800AF5-A	Qimonda		6/27/05	Yes	(64Mx8)* 18	DR	
Micron	MT18HTF12872Y-40EB3	MT47H64M8BT-5E	Micron		6/27/05	Yes	(128Mx4)* 18	SR	
Samsung	M393T2950CZ0-CCC	K45T1043QC-ZCCC	Samsung		6/27/05	Yes	(128Mx4)* 18	SR	
+ATP Electronics	AH28K72M4BHC4S	K4T51043QB-GCCC rev B	Samsung	SH240M04K1	07/08/05		(128Mx4)* 18	SR	
+Kingston	KVR400D2S4R3/1GI	E5104AE-5C-E rev E	Elpida	2025248-001.B00	07/14/05		(128Mx4)* 18	SR	
+Legacy Electronics Inc.	B512872M20A-50A	K4T51043QB-GCCC rev B	Samsung	LE18DD2F2404RRH rev A	07/18/05		(128Mx4)* 18	SR	
+Smart Modular Technologies	SB1287RDR21243-5-E	E5104AB-4A-E rev B	Elpida	Z10 026A na	08/18/05		(128Mx4)* 18	SR	
+Legacy Electronics Inc.	S512872M20A-50A	HYB18T512400AF(C)5 rev A	Qimonda	LE18DD2F2404RRH rev A	08/11/05		(128Mx4)* 18	SR	
+Smart Modular Technologies	SB1287RDR21243-5-H	HY5PS12421FP-E3 A 1st Generation	Hynix	E72369 na	08/05/05		(128Mx4)* 18	SR	
+Viking	VR5ER287218EB-PL3	MT47H64M8CB-37E rev B	Micron	0000992A rev A	08/01/05		(64Mx8)* 18	DR	
+Wintec Industries	39C931344B-GL	K4T51043QB-ZCCC rev B	Samsung	D2R472 na	08/03/05		(128Mx4)* 18	SR	
+Smart Modular Technologies	SB1287RDR2124351A	HYB18T512400AF5 rev A	Qimonda	PB54G240N ESUBRCC1 rev A	9/21/05		(128Mx4)* 18	SR	
+Dataram	DTM63310A	HYB18T512400AF5 rev A	Qimonda	40011A rev A	10/6/05		(128Mx4)* 18	SR	
+Kingston	KVR400D2S8R3/1GI	HYB18T1G800AF-5 rev A	Qimonda	2025263-001.C00	9/29/05		(128Mx8)* 9	SR	
Samsung	M393T2950CZ3-CCC	K4T51043QC-ZCCC	Samsung		10/12/05	Yes	(128Mx4)* 18	SR	
+Dataram	DTM63327A	HYB18T512800AF5 rev A	Qimonda (Infineon)	40056A rev A	10/28/05		(64Mx8)* 18	DR	

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
+Legend	L12723C7-RCAH2HBF	HY5PS12821F-E3 rev A	Hynix	B62RRCA rev A	11/7/05		(64Mx8)*18	DR	
Hynix	HYMP512R724-E3	HY5PS12421-F-E3	Hynix		10/24/05		(128Mx4)*18	SR	
Samsung	M393T2953CZ3-CCC	K4T510830C-ZCCC	Samsung		11/1/05	Yes	(64Mx8)*18	DR	
+Kingston	KVR400D2S4R3/1GI	HYB18T512400AF5 rev A	Qimonda	2025248-001.B00 na	11/14/05		(128Mx4)*18	SR	
+Ventura Technology Group	D2-54KF53SV-333	K4T51043QB-ZCCC rev B	Samsung	D2R472	1/9/06	Yes	(128Mx4)*18	SR	
Hynix	HYMP512R72P4-E3	HY5PS12421FP-E3	Hynix		1/10/06	Yes	(128Mx4)*18	SR	
Hynix	HYMP512R72P8-E3	HY5PS12821FP-E3	Hynix		1/10/06	Yes	(64Mx8)*18	DR	
Hynix	HYMP112R72P8-E3	HY5PS1G831FP-E3	Hynix		1/10/06	Yes	(128Mx8)*9	SR	
+Kingston	KVR400D2S4R3/1GI	HYB18T512400AF3 7 rev A	Qimonda	2025248-001.B00 na	1/18/06	Yes	(128Mx4)*18	SR	
+Wintec Industries	39S931341A-L	HYB18T512400AF5 rev A	Qimonda	D2R472	1/23/06	Yes	(128Mx4)*18	SR	
+Apacer	75.072A1.G02	K4T51043QC-ZCD5 rev C	Samsung	48.16189.01 1 rev 1	1/25/06	Yes	(128Mx4)*18	SR	
Hynix	HYMP512R72BP4-E3	HY5PS12421BFP-E3	Hynix		1/31/06	Yes	(128Mx4)*18	SR	
Hynix	HYMP512R72BP8-E3	HY5PS12821BFP-E3	Hynix		1/31/06	Yes	(64Mx8)*18	DR	
+Smart Modular Technologies	SG1287RDR2648 35IA	HYB18T512800AF3 7 rev A	Qimonda	PG58G240N EBUB2RB rev A	2/7/06		(64Mx8)*18	DR	
+Legacy Electronics Inc.	B517M4C2AHA-50	K4T51043QC-ZCCC rev C	Samsung	LE18DD2F2 404RRH rev A	2/16/06		(128Mx4)*18	SR	
+Smart Modular Technologies	SG1287RDR2648 35SC	K4T51083QC-ZCD5 rev C	Samsung	PG58G240N EBUB2RB rev A	3/7/06	Yes	(64Mx8)*18	DR	
TRS	TRS31265	HYB18T512400AF5 rev A	Qimonda	M0549LA1 rev 1	03/29/06	Yes			
Dataram	DTM63310J	NT5TU128M4AE-5A rev A	Nanya	40011A rev A	04/03/06	Yes			
Kingston	KVR400D2S8R3/1GI	E1108AA-5C-E rev A	Elpida	2025263-001.C00 na	05/03/06	Yes			
Dataram	DTM63327B	NT5TU64M8AE-37B rev A	Nanya	40056A rev A	05/08/06	Yes	(64Mx8)*18	DR	

**Registered, ECC, DDR2-400 DIMM Modules
1GB Size (128M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Kingston	KVR400D2S4R3/1GI	NT5U128M4AE-5A rev A	Nanya	2025248-001.B00 na	6/6/06	Yes	(128Mx4)*18	SR	
Smart Modular Technologies	SG1287RDR212435NA	NT5TU128M4AE-5A rev A	Nanya	NTPCB00019P	7/7/06	Yes	(128Mx4)*18	SR	
TRS	TRS31267	K4T51043QC-ZCCC rev C	Samsung	M0549LA1 rev 1	6/23/06	Yes	(128Mx4)*18	SR	
Super Talent Electronics	T400RA1G4/S1G TR4BHS	K4T51043QC-ZCD5 rev C	Samsung	DR20418 rev H1.01	8/11/06	Yes	(128Mx4)*18	SR	
Super Talent Electronics	T400RB1G/S1GT R8CHS	K4T51083QC-ZCD5 rev C	Samsung	DR20818 rev G1.01	8/18/06	Yes	(64Mx8)*18	DR	
Avant Technology	AVF7228R53E3400F0-MTB	MT47H128M4CB-5E rev B	Micron	50-1435-01B rev B	8/24/06	Yes	(128Mx4)*18	SR	
TRS	TRS31265X	HYB18T512400AF5 rev A	Qimonda (Infineon)	M0549LA1 rev 1	8/28/06	Yes	(128Mx4)*18	SR	
Avant Technology	AVF7228R52E3400F0-ELGP	EDE5108AGBG-5C-E rev G	Elpida	50-1431-01B rev B	9/6/06	Yes	(64Mx8)*18	DR	
Kingston	KVR400D2S4R3/1GI	E5104AG-5C-E rev G	Elpida	2025248-001.B00 na	10/12/06	Yes	(128Mx4)*18	SR	
Kingston	KVR400D2S8R3/1GI	E1108AB-6E-E rev B	Elpida	2025263-001.C00 na	11/21/06	Yes	(128Mx8)*9	SR	
TRS	TRS31277X	E5104AG-5C-E rev G	Elpida	M0549LA1 rev 1	2/15/07	Yes	(128Mx4)*18	SR	
All Components	AVF7228R52E3400F0-ELGP	EDE5108AGBG-5C-E rev G	Elpida	50-1431-01B rev B	2/23/07	Yes	(64Mx8)*18	DR	
US Technology	AVF7228R52E3400F0-ELGP	EDE5108AGBG-5C-E rev G	Elpida	50-1431-01B rev B	3/24/07	Yes	(64Mx8)*18	DR	
Kingston	KVR400D2S8R3/1GI	MT47H128M8HQ-3 rev E	Micron	2025263-001.C00 na	4/16/07	Yes	(128Mx8)*9	SR	
Dataram	DTM63327C	HY5PS12821CFP-Y5 rev C	Hynix	40056A rev A	4/19/07	Yes	(64Mx8)*18	DR	
Dataram	DTM63310N	HY5PS12421CFP-Y5 rev C	Hynix	40011A rev A	4/20/07	Yes	(128Mx4)*18	SR	
Kingston	KVR400D2S4R3/1GI	E5104AHSE-6E-E rev H	Elpida	2025248-001.B00 na	5/2/07	Yes	(128Mx4)*18	SR	
Dane-Elec	DMD400R072283NG	EDE5108AESK-5C-E rev E	Elpida	D2R872 rev 1	7/16/07	Yes	(64Mx8)*18	DR	
Smart Modular Technologies	SG1287RDR212435IB	HYB18T512400BF37 rev B	Qimonda	PG54G240N ESUBRCC1 rev A	10/19/07	Yes	(128Mx4)*18	SR	
Kingston	KVR400D2S4R3/1GI	NT5TU128M4BE-3C rev B	Nanya	2025248-001B00	12/19/07	Yes	(128Mx4)*18	SR	

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Intel® Server Board SE7320VP2
Registered, ECC, DDR266 DIMM Modules
2GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
+TRS	TRS21155	HYB25D512400AT-7 rev A	Qimonda	M0531LA1 rev 1	11/12/04		(128Mx4)* 36	DR	
+Ventura Technology Group	D56WXK28SV	K4H510438B-TCB3 rev B	Samsung	V213	11/18/04		(128Mx4)* 36	DR	
+Viking	VI4CR567224EY HL3	K4H510438B-TCB3 rev B	Samsung	03-0307 rev B	12/15/04		(128Mx4)* 36	DR	
+ATP Electronics	AB56L72T4SHB0S	K4H510438B-TCB3 rev B	Samsung	SB184T04L3	1/25/05		(128Mx4)* 36	DR	
+Avant Technology	AVM7256R53C5266K7-MTD	MT46V128M4FN-6 rev D	Micron	E186014	5/31/05		(128Mx4)* 36	DR	
+Dataram	DTM63689D	HYB25D512400BF(BC)-6 rev B	Qimonda	40020A rev A	6/6/05		128M x 4		
+TRS	TRS21218	HYB25D512400BE-7 rev B	Qimonda	M0531LA1 rev 1	08/02/05		(128Mx4)* 36	DR	
Micron	MT36VDDDF25672G-265D2	MT46V128M4FN	Micron		10/24/05		(128Mx4)* 36	DR	
Samsung	M312L5628BT0-CB0	K4H1G0638B-TCB0	Samsung		7/29/05		(128Mx4)* 36		
Samsung	M312L5628CU0-CB0	K4H1G0638C-UCB0	Samsung		8/19/05	Yes	(128Mx4)* 36		
+Dataram	DTM63689J	HYB25D512400CF-6 rev C	Qimonda	40020A rev A	3/22/06	Yes	(128Mx4)* 36	DR	

Registered, ECC, DDR333 DIMM Modules 2GB Size (256M x 72)									
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
+Smart Modular Technologies	SM25672RDDR6 H2BGAI	HYB25D512400BC-6 rev B	Qimonda	P54G184NESZ B1RF rev A	11/15/04		(128Mx4) *36	DR	
+Legacy Electronics Inc.	8AL6MDGM-1PDG	BGA128MX4DDRNC	Legacy	LE36DDF1844 RRF rev B	12/9/04		(128Mx4) *36	DR	
+Apacer	75.A7299.570	HYB25D512400BC-6 rev B	Qimonda	48.16164.014 rev 4	12/15/04		(128Mx4) *36	DR	
+Smart Modular Technologies	SM25672RDDR6 H2BGBI	HYB25D512400BC-6 rev B	Qimonda	184-25-2	1/14/05		(128Mx4) *36	DR	
+ATP Electronics	AB56L72Z4BFB3C	HYB25D512400BC-6 rev B	Qimonda	SB184Z04L1	1/31/05		(128Mx4) *36	DR	
Qimonda	HYS72D256320G BR-6-B	HYB25D512400BC-6 B	Qimonda		3/2/05		(128Mx4) *36	DR	
+Dataram	DTM63680H	MT46V128M4BN-6 rev D	Micron	40020A rev A	2/25/05		(128Mx4) *36	DR	
Qimonda	HYS72D256320G BR-6-B	HYB25D512400BC-6 B	Qimonda		3/2/05		(128Mx4) *36	DR	
+Dataram	DTM63680F	HYB25D512400BF(C)-6 rev B	Qimonda	40020A rev A	3/15/05		(128Mx4) *36	DR	
Micron	MT36VDDF25672 G-335D2	MT46V128M4FN	Micron		4/6/05		(128Mx4) *36	DR	
+Kingston	KVR333D4R25/2 GI	HYB25D512400BC-6 rev B	Qimonda	2025294-001.A00	4/4/05		(128Mx4) *36	DR	
Netlist*, Incorporated	NL9257RD12032-D27JSC	K4H510438C-ZCB3 rev C	Samsung	0175-10 rev A	4/27/05		(128Mx4) *36	DR	
+Avant Technology	AVM7256R53C53 33K7-MTD	MT46V128M4FN-6 rev D	Micron	B6R404 rev 1	5/4/05		(128Mx4) *36	DR	
Samsung	M312L5720CZ0-CB3	K4H510438C-ZCB3	Samsung		6/20/05	Yes	(128Mx4) *36	DR	
+Kingston	KVR333D4R25/2 GI	MT46V128M4FN-6 rev D	Micron	2025294-001.A00 na	10/11/05		(128Mx4) *36	DR	
Samsung	M312L5720CZ3-CB3	K4H510438C-ZCB3	Samsung		11/15/05	Yes	(128Mx4) *36	DR	
Samsung	M312L5628BT0-CB0	K4H1G0638B-TCB0	Samsung		11/15/05		(128Mx4) *36	DR	
Samsung	M312L5628CU0-CB0	K4H1G0638C-UCB0	Samsung		11/15/05	Yes	(128Mx4) *36	DR	
Qimonda	HYS72D256320H BR-6-C	HYB25D512400CF-6	Qimonda		1/31/06	Yes	(128Mx4) *36	DR	
+TRS	TRS21225	HYB25D512400BC-6 rev B	Qimonda	M0546LA1 rev 1	3/2/06		(128Mx4) *36	DR	
Dataram	DTM63680P	HYB25D512400CF-6 rev C	Qimonda (Infineon)	40020A rev A	04/10/06				
Kingston	KVR333D4R25/2 GI	K4H510438C-ZCB3 rev C	Samsung	2025294-001.A00 na	7/25/06	Yes	(128Mx4) *36	DR	
Kingston	KVR333D4R25/2 GI	HYB25D512400CF-5 rev C	Qimonda	2025294-001.A00 na	4/13/07	Yes	(128Mx4) *36	DR	
Kingston	KVR333D4R25/2 GI	HYB25D512400BF-5 rev B	Qimonda	2025294-001.A00 na	9/25/07	Yes	(128Mx4) *36	DR	

**Registered, ECC, DDR2-400 DIMM Modules
2GB Size (256M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Hynix	HYMP125R724-E3	HY5PS1G431F-E3	Hynix		5/23/05		(256Mx4)* 18	SR	
Qimonda	HYS72T256220H R-5-A	HYB18T512400AF5	Qimonda		5/23/05	Yes	(128Mx4)* 36	SR	
Qimonda	HYS72T256000H R-5-A	HYB18T1G400AF-5	Qimonda		6/6/05	Yes	(256Mx4)* 18	SR	
Samsung	M393T5660MZ0-CCC	K4T1G044QM-ZCCC	Samsung		6/6/05	Yes	(256Mx4)* 18	SR	
Micron	MT18HTF25672Y-40EA2		Micron		6/27	Yes	(256Mx4)* 18	SR	
Micron	MT36HTF25672Y-40EB1		Micron		7/8/05	Yes	(128Mx4)* 36		
+Smart Modular Technologies	SB2567RDR2128 35IA	HYB18T512400AF5 rev A	Qimonda	PB52G240NES UB1RJ rev A	07/22/05		(128Mx4)* 36	DR	
+Smart Modular Technologies	SG2567RDR2128 35IA	HYB18T512400AF5 rev A	Qimonda	PG52G240NES UB1RJ rev A	07/12/05		(128Mx4)* 36	DR	
+Smart Modular Technologies	SM2567RDR2254 3-5-I	HYB18T1G400AF-5 rev A	Qimonda	240-13-5	07/18/05		(256Mx4)* 18	SR	
+Kingston	KVR400D2D8R3/2GI	HYB18T1G800AF-5 rev A	Qimonda	2025302-001.A00 na	08/23/05		128M x 8		
+Dataram	DTM63309A	HYB18T512400AF5 rev A	Qimonda	40040A rev A	08/16/05		(128Mx4)* 36	DR	
+Dataram	DTM63309B	K4T51043QC-ZCCC rev C	Samsung	40040A rev A	08/18/05		(128Mx4)* 36	DR	
+Wintec Industries	39C941441A-L	HYB18T1G400AF-5 rev A	Qimonda	D2R472 na	8/29/05		(256Mx4)* 18	SR	
Samsung	M393T5750CZ0-CCC	K45T1043QC-ZCCC	Samsung		9/20/05	Yes	(128Mx4)* 36	DR	
+Smart Modular Technologies	SG2567RDR2128 3-5-H	HY5PS1G421MP-E3 rev A	Hynix	(0504-5,-3,-1),(0518-1,-2,-3,-4,-6),(0516-1,-3)	10/26/05	Yes	(128Mx4)* 36	DR	
Samsung	M393T5750BS0-CCC	K45T1043QB-SCCC	Samsung		11/1/05		(128Mx4)* 36	DR	
Samsung	M393T5750BY0-CCC	K45T1043QB-ZCCC	Samsung		11/1/05	Yes	(128Mx4)* 36	DR	
Hynix	HYMP125R72P4-E3	HY5PS1G431FP-E3	Hynix		11/1/05		(256Mx4)* 18	SR	
Samsung	M393T5750CZ3-CCC	K45T1043QC-ZCCC	Samsung		11/4/05	Yes	(128Mx4)* 36	DR	
Samsung	M393T5660MZ3-CCC	K4T1G044QM-ZCCC	Samsung		11/4/05	Yes	(256Mx4)* 18	SR	
+Legacy Electronics Inc.	B527M4C2BJA-50	K4T51043QC-ZCCC rev C	Samsung	LE36DD2F240 4RRJ rev B	11/21/05		(128Mx4)* 36	DR	
+ATP Electronics	AH56K72M4BJC4 C	HYB18T1G400AF-5 rev A	Qimonda	SH240M04K1 na	12/9/05	Yes	(256Mx4)* 18	SR	
+Kingston	KVR400D2D4R3/2GI	HYB18T512400AF5 rev A	Qimonda	2025292-001.B00 na	12/13/05		(128Mx4)* 36	DR	
Samsung	M393T5660AZ3-CCC	K4T1G044QA-ZCCC	Samsung		11/15/05	Yes	(256Mx4)* 18	SR	

**Registered, ECC, DDR2-400 DIMM Modules
2GB Size (256M x 72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Hynix	HYMP125R72P8-E3	HY5PS1G831FP-E3	Hynix		1/31/06	Yes	(128Mx8)* 18		
Hynix	HYMP525R72BP4-E3	HY5PS12421BFP-E3	Hynix		1/31/06	Yes	(128Mx4)* 36	DR	
+Legend	L25723C7-R41H2W2F	HY5PS1G421MP-E3 rev 1st Gen.	Hynix	0536	2/28/06	Yes	(256Mx4)* 18	SR	
+TRS	TRS31270	HYB18T1G400AF-5 rev A	Qimonda	M0549LA1 rev 1	3/20/06	Yes	(256Mx4)* 18	SR	
Kingston	KVR400D2D4R3/2GI	HYB18T512400AF3 7 rev A	Qimonda	2025292-001.B00 na	04/17/06	Yes			
Kingston	KVR400D2D8R3/2GI	E1108AA-5C-E rev A	Elpida	2025302-001.A00 na	05/11/06	Yes	(128Mx8)* 18		
Dataram	DTM63309F	NT5TU128M4AE-5A rev A	Nanya	40040A rev A	05/19/06	Yes	(128Mx4)* 36	DR	
Kingston	KVR400D2D4R3/2GI	NT5TU128M4AE-5A rev A	Nanya	2025292-001.B00 na	6/16/06	Yes	(128Mx4)* 36	DR	
TRS	TRS31270X	HYB18T1G400AF-5 rev A	Qimonda (Infineon)	M0549LA1 rev 1	8/8/06	Yes	(256Mx4)* 18	SR	
Super Talent Electronics	T400RB2G4/S2G TR4CHS	K4T51043QC-ZCD5 rev C	Samsung	BA2RRCJ na	8/16/06	Yes	(128Mx4)* 36	DR	
Kingston	KVR400D2D4R3/2GI	E5104AG-5C-E rev G	Elpida	2025292-001.B00 na	10/10/06	Yes	(128Mx4)* 36	DR	
ATP Electronics	AH56K72M4BJC4 C	HYB18T1G400AF-5 rev A	Qimonda (Infineon)	SH240M04K2 na	11/28/06	Yes	(256Mx4)* 18	SR	
Smart Modular Technologies	SG2567RDR2124 35NB	NT5TU128M4BE-3C rev B	Nanya	PG52G240NES UB3RJ rev A	12/4/06	Yes	(128Mx4)* 36	DR	
Kingston	KVR400D2D8R3/2GI	E1108AB-6E-E rev B	Elpida	2025302-001.A00 na	12/7/06	Yes	(128Mx8)* 18		
Kingston	KVR400D2D8R3/2GI	MT47H128M8HQ-3 rev E	Micron	2025302-001.A00 na	4/13/07	Yes	(128Mx8)* 18		
Dataram	DTM63309J	HY5PS12421CFP-Y5 rev C	Hynix	40040A rev A	4/25/07	Yes	(128Mx4)* 36	DR	
Kingston	KVR400D2D4R3/2GI	E5104AHSE-6E-E rev H	Elpida	2025292-001.C00 na	5/3/07	Yes	(128Mx4)* 36	DR	
Smart Modular Technologies	SG2567RDR2124 35SE	K4T51043QE-ZCE6 rev E	Samsung	PG52G240NES UB3RJ rev A	10/23/07	Yes	(128Mx4)* 36	DR	
Kingston	KVR400D2D4R3/2GI	NT5TU128M4BE-3C rev B	Nanya	2025292-001.C00 na	12/20/07	Yes	(128Mx4)* 36	DR	
Kingston	KVR400D2D8R3/2GI	HY5PS1G831CFP-Y5 rev C	Hynix	2025302001.A00 na	2/26/08	Yes	(128Mx8)* 18		
Kingston	KVR400D2D4R3/2GI	HYB18T512400AF3 7 rev A	Qimonda	2025292-001.C00 rev C	04/18/08	Yes	(128Mx8)* 18		

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Verify that the DRAM part number matches the DRAM on this list before purchasing.

Intel® Server Board SE7320VP2
Registered, ECC, DDR266 DIMM Modules
4GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Samsung	M312L5128MT0-CB0	K4H2G0638M-TCB0	Samsung		6/20/05		(256Mx4) *36	SR	
+Dataram	DTM63687C	K4H1G0438M-TCB0 rev M	Samsung	40556 rev B	08/04/05		(256Mx4) *36		
+ATP Electronics	AB12L72P4SMB0S	K4H2G0638M-TCB0 rev M	Samsung	M312L2828T0B GA-V01	12/8/05		(256Mx4) *36	SR	

Registered, ECC, DDR333 DIMM Modules
4GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Micron	MT36VDDT51272G-265A2	MT46V256M4TG-75A	Micron		6/27/05		(256Mx4) *36		

Registered, ECC, DDR2-400 DIMM Modules
4GB Size (256M x 72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	Lead-Free	DRAM Organization	Rank	EOL
Qimonda	HYS72T512022HR-5-A	HYB18T2G402AF-5-A	Qimonda		11/1/05	Yes	(2x256Mx4)*18		
+Smart Modular Technologies	SG5127RDR225635IA	HYB18T1G400AF-5 rev A	Qimonda	PG516G240NE SUC1RK rev A	11/14/05	Yes	(256Mx4) *36		
+Kingston	KVR400D2D4R3/4GI	E1104AA-4A-E rev A	Elpida	2025343-001.A00 na	12/16/05		(256Mx4) *36		
Hynix	HYMP351R72MP4-E3	HY5PS2G431MP-E3	Hynix		1/10/06	Yes	(256Mx4) *36		
Kingston	KVR400D2D4R3/4GI	K4T2G064QA-ZCD5 rev A	Samsung	M393T1G68MG1 na	04/07/06	Yes			
Dataram	DTM63325A	HYB18T1G400AF-5 rev A	Qimonda (Infineon)	40054A rev D	04/24/06	Yes			
Smart Modular Technologies	SG5127RDR225635ART	HYB18T1G400AF-5 rev A	Qimonda	XG58G240NES UB1TK rev A	1/8/07	Yes	(256Mx4) *36		
Kingston	KVR400D2D4R3/4GI	E1108ABSH-E rev B	Elpida	Z10077 na	2/22/07	Yes	(256Mx4) *36		

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Verify that the DRAM part number matches the DRAM on this list before purchasing.

4. Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpinc.com/	Tel (1) 408-732-5000, ext 5858 Fax 408-732-5893 sales@atpusa.com
ATP Electronics -- Taiwan Inc.	http://www.atpinc.com/	Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 phenke@dataram.com
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.hea.com/	
Qimonda	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itauc.com.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Gary Ridenour, 949-498-9600, Ext 350 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/ http://silicon.micron.com/mktg/mbqual/qual_data.cfm	
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com
Peripheral Enhancements	http://www.peripheral.com/	

Vendor Name	Web URL	Vendor Direct Sales Info
Samsung	http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	www.smartm.com/channel/hpc/	Gene Patino (949) 439-6167 Gene.Patino@Smartm.com
Swissbit	http://www.swissbit.com	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 tony.cerreta@swissbitna.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http://www.certified-memory.com http://www.certified-memory.de	Vendor Direct Sales Info: Andreas Gruendl Tel: +49.89.945532-34 Fax: +49.89.945532-41 Andreas.gruendl@trs-eu.com
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Sam Lewis 760 724-8700 ext. 103
Viking InterWorks	http://www.vikinginterworks.com	Adrian Proctor Tel: 949-643-7255 adrian.proctor@sanmina-sci.com
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

5. CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Qualification Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

IMPORTANT NOTE

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each Rank on the memory module. Mixing of dissimilar memory manufacturer devices or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with the Intel® Server RAID Controller. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the Intel® Server RAID Controller. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server RAID Controller product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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